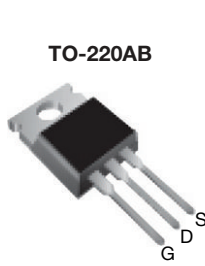


Power MOSFET



N-Channel MOSFET

FEATURES

- Low gate charge Q_g results in simple drive requirement
- Improved gate, avalanche, and dynamic dV/dt ruggedness
- Fully characterized capacitance and avalanche voltage and current
- Low $R_{DS(on)}$
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- High speed power switching
- Hard switched and high frequency circuits

PRODUCT SUMMARY

| | | |
|---------------------------|------------------------|------|
| V_{DS} (V) | 500 | |
| $R_{DS(on)}$ (Ω) | $V_{GS} = 10\text{ V}$ | 0.21 |
| Q_g max. (nC) | 110 | |
| Q_{gs} (nC) | 33 | |
| Q_{gd} (nC) | 54 | |
| Configuration | Single | |

ORDERING INFORMATION

| | |
|----------------|----------------|
| Package | TO-220AB |
| Lead (Pb)-free | IRFB20N50KPbF |
| | SiHFB20N50K-E3 |

ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted)


| PARAMETER | SYMBOL | LIMIT | UNIT | |
|---|----------------------------------|-----------------------------------|--------------------|---|
| Drain-source voltage | V_{DS} | 500 | V | |
| Gate-source voltage | V_{GS} | ± 30 | | |
| Continuous drain current | V_{GS} at 10 V | $T_C = 25\text{ }^\circ\text{C}$ | A | |
| | | $T_C = 100\text{ }^\circ\text{C}$ | | |
| Pulsed drain current ^a | I_{DM} | 80 | | |
| Linear derating factor | | 2.2 | $W/^\circ\text{C}$ | |
| Single pulse avalanche energy ^b | E_{AS} | 330 | mJ | |
| Repetitive avalanche current ^a | I_{AR} | 20 | A | |
| Repetitive avalanche energy ^a | E_{AR} | 28 | mJ | |
| Maximum power dissipation | $T_C = 25\text{ }^\circ\text{C}$ | P_D | 280 | W |
| Peak diode recovery dV/dt ^c | dV/dt | 10 | V/ns | |
| Operating junction and storage temperature range | T_J, T_{stg} | -55 to +150 | $^\circ\text{C}$ | |
| Soldering recommendations (peak temperature) ^d | For 10 s | 300 | | |
| Mounting torque | 6-32 or M3 screw | 10 | N | |

Notes

- Repetitive rating; pulse width limited by maximum junction temperature
- Starting $T_J = 25\text{ }^\circ\text{C}$, $L = 1.6\text{ mH}$, $R_g = 25\text{ }^\circ\Omega$, $I_{AS} = 20\text{ A}$
- $I_{SD} \leq 20\text{ A}$, $dI/dt \leq 350\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 150\text{ }^\circ\text{C}$
- 1.6 mm from case



| THERMAL RESISTANCE RATINGS | | | | |
|-------------------------------------|------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum junction-to-ambient | R_{thJA} | - | 58 | °C/W |
| Case-to-sink, flat, greased surface | R_{thCS} | 0.50 | - | |
| Maximum junction-to-case (drain) | R_{thJC} | - | 0.45 | |

| SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted) | | | | | | | |
|---|-----------------------|---|--|------|-----------|---------------|----|
| = 25 °C, | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT | |
| Static | | | | | | | |
| Drain-source breakdown voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | 500 | - | - | V | |
| V_{DS} temperature coefficient | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^\circ\text{C}, I_D = 1\text{ mA}$ | - | 0.61 | - | V/°C | |
| Gate-source threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | 3.0 | - | 5.0 | V | |
| Gate-source leakage | I_{GSS} | $V_{GS} = \pm 30\text{ V}$ | - | - | ± 100 | nA | |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$ | - | - | 50 | μA | |
| | | $V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$ | - | - | 250 | | |
| Drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}, I_D = 12\text{ A}^b$ | - | 0.21 | 0.25 | Ω | |
| Forward transconductance | g_{fs} | $V_{DS} = 50\text{ V}, I_D = 12\text{ A}$ | 11 | - | - | S | |
| Dynamic | | | | | | | |
| Input capacitance | C_{iss} | $V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}, \text{ see fig. 5}$ | - | 2870 | - | pF | |
| Output capacitance | C_{oss} | | - | 320 | - | | |
| Reverse transfer capacitance | C_{rss} | | - | 34 | - | | |
| Output capacitance | C_{oss} | $V_{GS} = 0\text{ V}$ | $V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$ | - | 3480 | - | |
| Effective output capacitance | $C_{oss\text{ eff.}}$ | | $V_{DS} = 400\text{ V}, f = 1.0\text{ MHz}$ | - | 85 | - | |
| Total gate charge | Q_g | $V_{GS} = 10\text{ V}$ | $V_{DS} = 0\text{ V to } 400\text{ V}$ | - | 160 | - | |
| Gate-source charge | Q_{gs} | | $I_D = 20\text{ A}, V_{DS} = 400\text{ V}$ see fig. 6 and 13 ^b | - | - | 110 | nC |
| Gate-drain charge | Q_{gd} | | | - | - | 33 | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD} = 250\text{ V}, I_D = 20\text{ A}$ $R_g = 7.5\text{ }\Omega, V_{GS} = 10\text{ V}, \text{ see fig. 10}^b$ | - | 22 | - | ns | |
| Rise time | t_r | | - | 74 | - | | |
| Turn-off delay time | $t_{d(off)}$ | | - | 45 | - | | |
| Fall time | t_f | | - | 33 | - | | |
| Gate input resistance | R_g | $f = 1\text{ MHz}, \text{ open drain}$ | 0.3 | - | 2.9 | Ω | |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous source-drain diode current | I_S | MOSFET symbol showing the integral reverse p - n junction diode  | - | - | 20 | A | |
| Pulsed diode forward current ^a | I_{SM} | | - | - | 80 | | |
| Body diode voltage | V_{SD} | $T_J = 25\text{ }^\circ\text{C}, I_S = 20\text{ A}, V_{GS} = 0\text{ V}^b$ | - | - | 1.5 | V | |
| Body diode reverse recovery time | t_{rr} | $T_J = 25\text{ }^\circ\text{C}, I_F = 20\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$ | - | 520 | 780 | ns | |
| Body diode reverse recovery charge | Q_{rr} | | - | 5.3 | 8.0 | μC | |
| Forward turn-on time | t_{on} | Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D) | | | | | |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. Pulse width $\leq 400\text{ }\mu\text{s}$; duty cycle $\leq 2\text{ }\%$



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

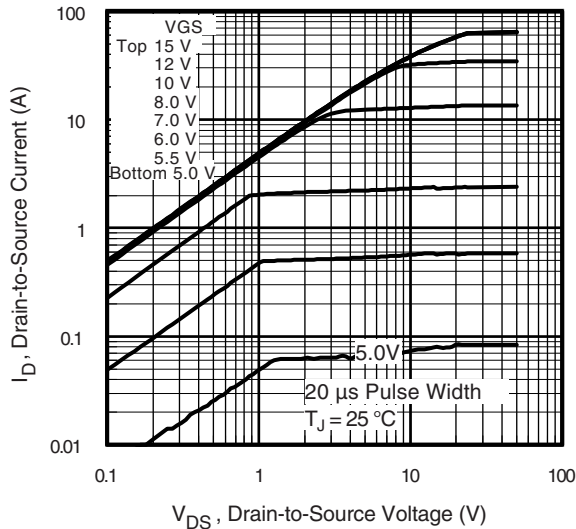


Fig. 1 - Typical Output Characteristics

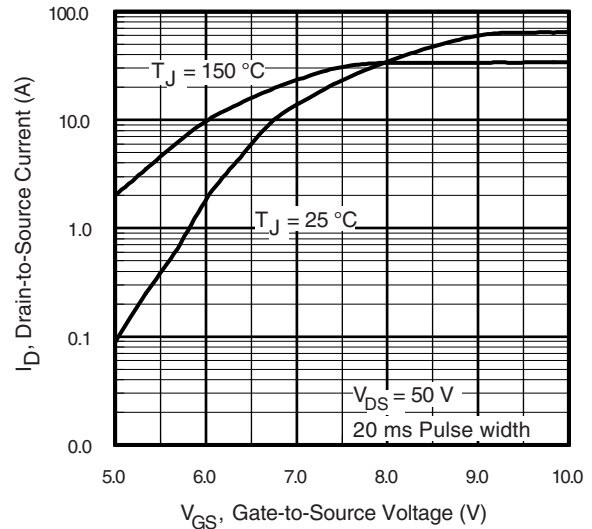


Fig. 3 - Typical Transfer Characteristics

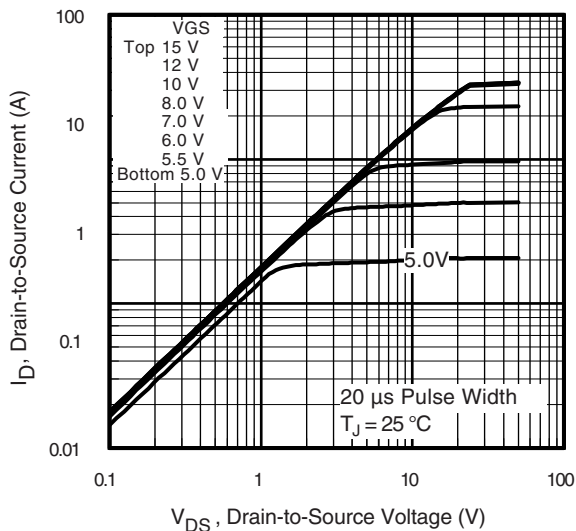


Fig. 2 - Typical Output Characteristics

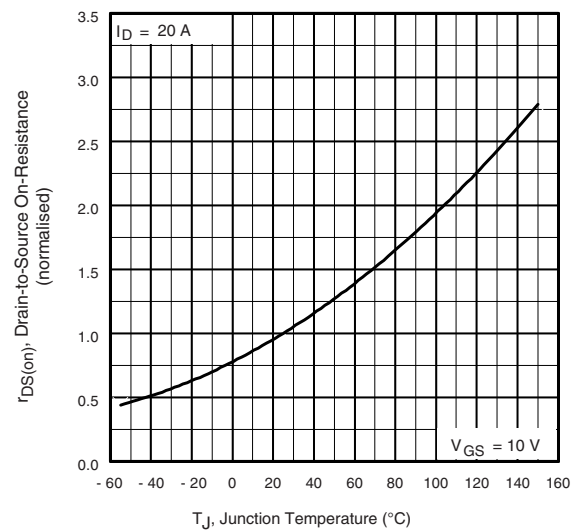


Fig. 4 - Normalized On-Resistance vs. Temperature

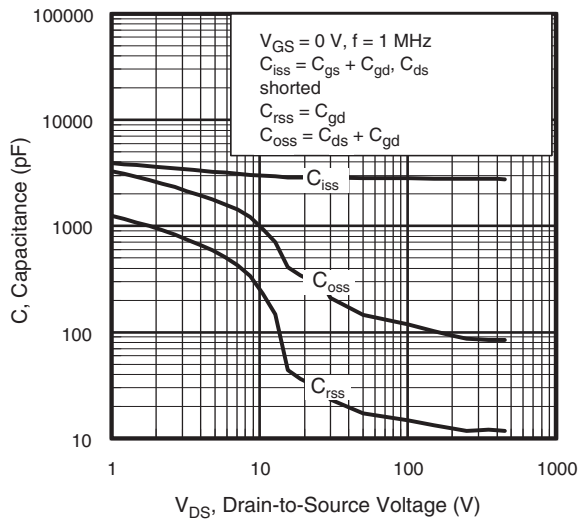


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

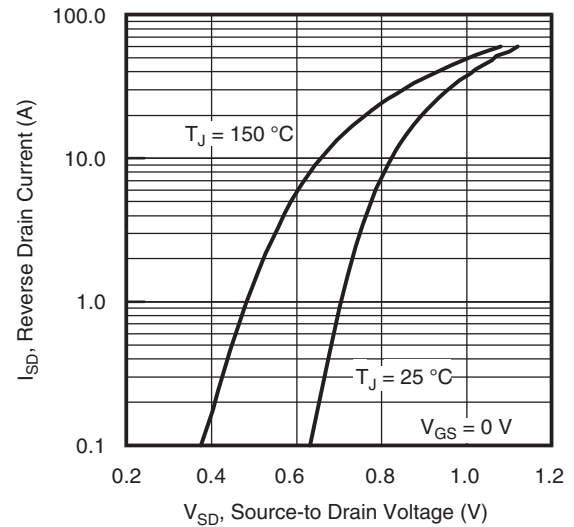


Fig. 7 - Typical Source-Drain Diode Forward Voltage

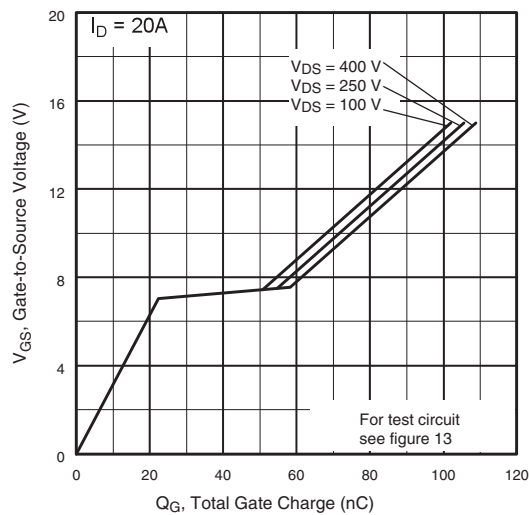


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

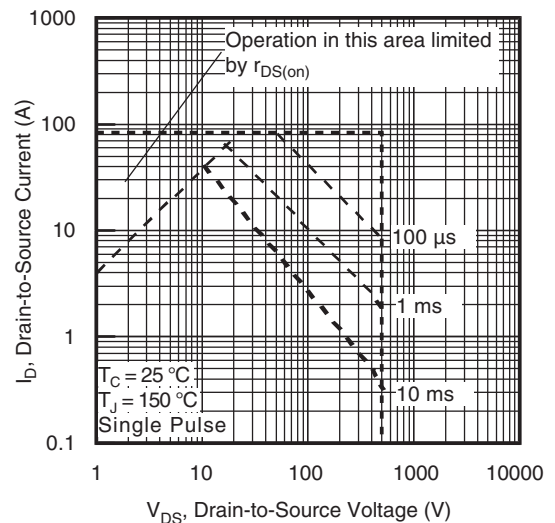


Fig. 8 - Maximum Safe Operating Area

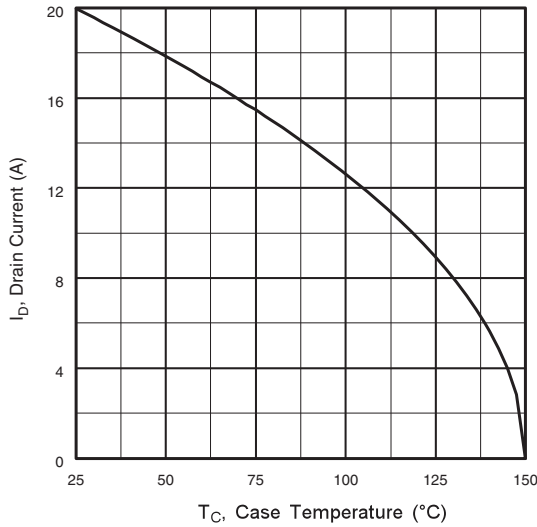


Fig. 9 - Maximum Drain Current vs. Case Temperature

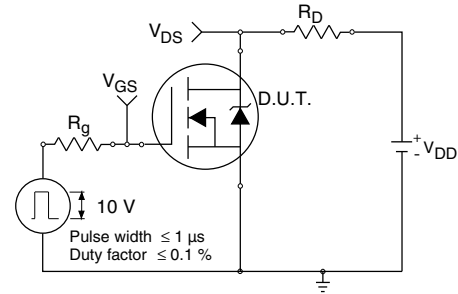


Fig. 10a - Switching Time Test Circuit

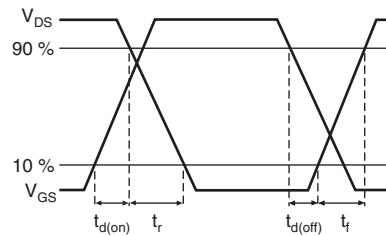


Fig. 10b - Switching Time Waveforms

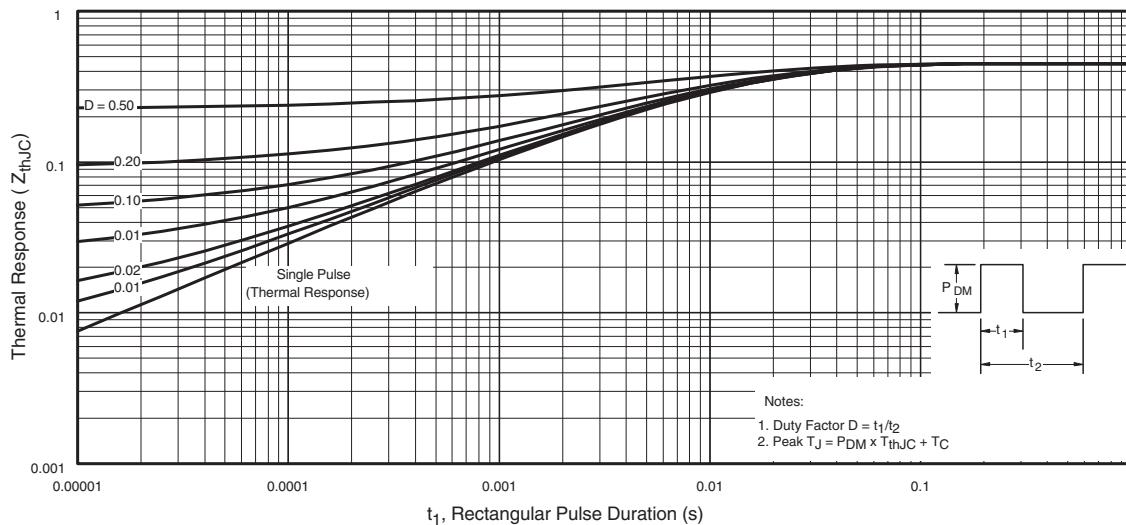


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

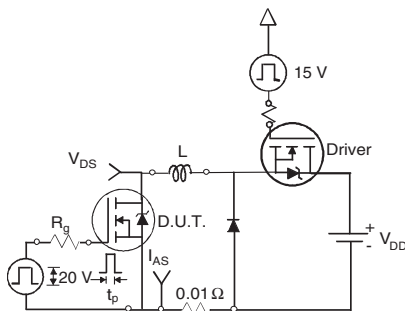


Fig. 12a - Unclamped Inductive Test Circuit

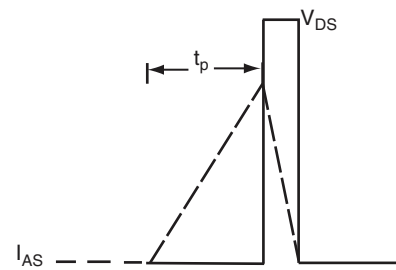


Fig. 12b - Unclamped Inductive Waveforms

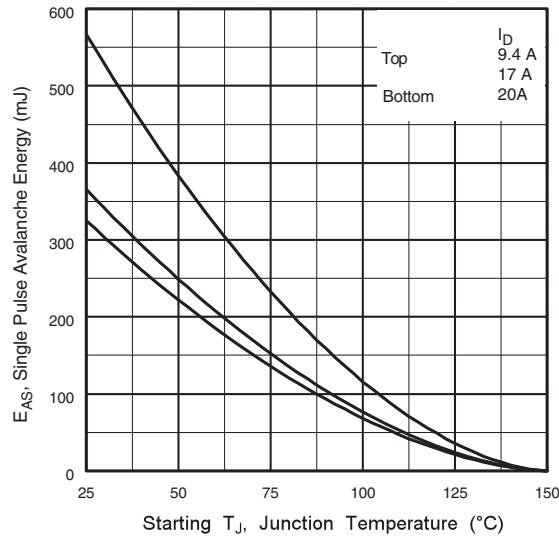


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

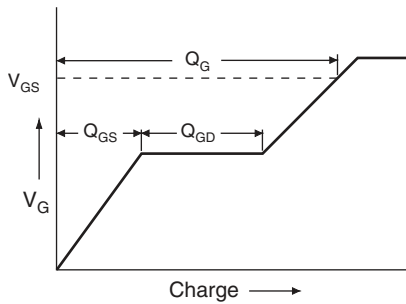


Fig. 13a - Basic Gate Charge Waveform

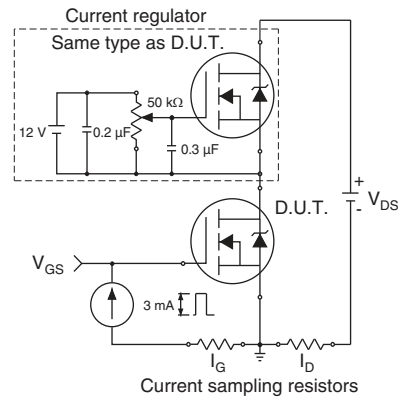
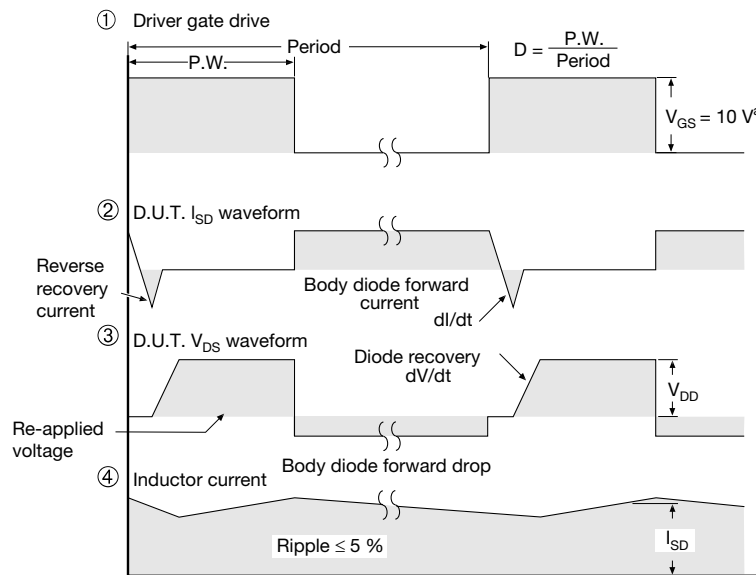
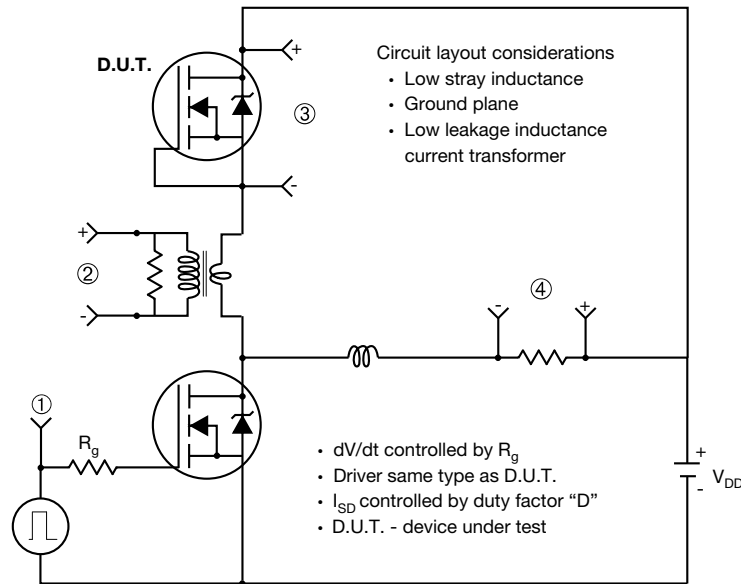


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



Note

a. $V_{GS} = 5 V$ for logic level devices

Fig. 14 - For N-Channel

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